

Overview

The purpose of this notification is to advise customers of a product marking change for SBGA packages. There is no change to the form, fit, or function.

Description

Xilinx will be converting the package top mark from ink to laser mark for all SBGA packages.

Products Affected

This change affects all speed, package, and temperature variations of the HiRel (XQ) devices. In addition, all associated specification control document (SCD) devices are affected as well. Affected device package combinations are included in the following Tables:

Table 1: Hirel (XQ) Product Affected

Xilinx Product	Xilinx Product	Xilinx Product
XQV1000-4BG560N	XQV300-4BG432NES	XQV300-4BG352N
XQV600-4BG432N	XQV300-4BG432N	XQV300-5BG352N

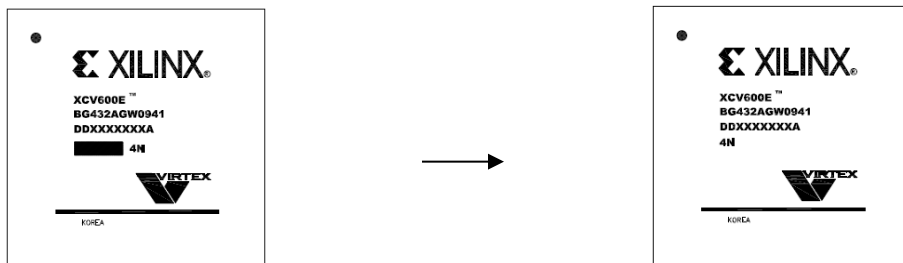
Key Dates and Ordering Information

Beginning on Nov 2nd, 2014 (date code: 1445), Xilinx will begin crossing shipping devices with either ink or laser mark until all ink inventory is depleted.

Traceability

Affected devices are identified by the following package top marks as shown in the [Figure 1](#).

Product marking example:



Current Marking (Black Ink)

New Marking (Laser)

Figure 1

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

Important Notice: Xilinx Customer Notifications (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the Support website (<http://www.xilinx.com/support>). Register today and personalize your Documentation and Design Advisory Alerts" area to include Customer Notifications. Xilinx Support provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to Answer Record 18683: <http://www.xilinx.com/support/answers/18683.htm>.

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/08/2014	1.0	Initial release.

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